

**PNP PRE-BIASED SMALL SIGNAL SURFACE MOUNT TRANSISTOR**
**Features**

- Epitaxial Planar Die Construction
- Complementary NPN Type Available (MMBT4401T)
- Ultra-Small Surface Mount Package
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

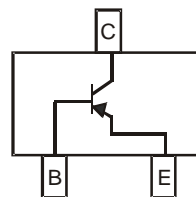
**Mechanical Data**

- Case: SOT523
- Case Material: Molded Plastic, "Green" Molding Compound
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 ③
- Weight: 0.002 grams (Approximate)

SOT523



Top View

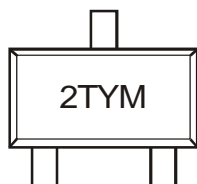


Package Pin Out Configuration

**Ordering Information** (Note 4)

Part Number	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
MMBT4403T-7-F	AEC-Q101	2T	7	8	3000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**


2T = Product Type Marking Code  
 YM = Date Code Marking  
 Y or  $\bar{Y}$  = Year (ex: F = 2018)  
 M = Month (ex: 9 = September)

## Date Code Key

Year	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028
Code	F	G	H	I	J	K	L	M	N	O	P

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@ $T_A = 25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	-40	V
Collector-Emitter Voltage	$V_{CEO}$	-40	V
Emitter-Base Voltage	$V_{EBO}$	-5.0	V
Collector Current – Continuous (Note 5)	$I_C$	-600	mA

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	$P_D$	150	mW
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{\theta JA}$	833	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

Note: 5. Mounted on FR4 PC Board with minimum recommended pad layout.

**Thermal Characteristics and Derating Information**

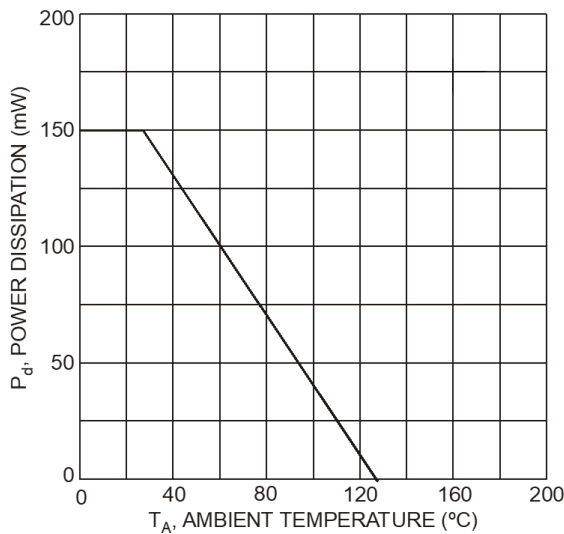


Fig. 1 Power Derating Curve, Total Package

**Electrical Characteristics** (@T<sub>A</sub> = 25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 6)</b>					
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	-40	—	V	I <sub>C</sub> = -100μA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	-40	—	V	I <sub>C</sub> = -1.0mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	-5.0	—	V	I <sub>E</sub> = -100μA, I <sub>C</sub> = 0
Collector Cutoff Current	I <sub>CEX</sub>	—	-100	nA	V <sub>CE</sub> = -35V, V <sub>EB(OFF)</sub> = -0.4V
Base Cutoff Current	I <sub>BL</sub>	—	-100	nA	V <sub>CE</sub> = -35V, V <sub>EB(OFF)</sub> = -0.4V
<b>ON CHARACTERISTICS (Note 6)</b>					
DC Current Gain	h <sub>FE</sub>	30	—	—	I <sub>C</sub> = -100μA, V <sub>CE</sub> = -1.0V
		60	—		
		100	—		
		100	300		
		20	—		
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	—	-0.40 -0.75	V	I <sub>C</sub> = -150mA, I <sub>B</sub> = -15mA I <sub>C</sub> = -500mA, I <sub>B</sub> = -50mA
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	-0.75 —	-0.95 -1.30	V	I <sub>C</sub> = -150mA, I <sub>B</sub> = -15mA I <sub>C</sub> = -500mA, I <sub>B</sub> = -50mA
<b>SMALL SIGNAL CHARACTERISTICS</b>					
Output Capacitance	C <sub>cb</sub>	—	8.5	pF	V <sub>CB</sub> = -10V, f = 1.0MHz, I <sub>E</sub> = 0
Input Capacitance	C <sub>eb</sub>	—	30	pF	V <sub>EB</sub> = -0.5V, f = 1.0MHz, I <sub>C</sub> = 0
Input Impedance	h <sub>ie</sub>	1.5	15	kΩ	V <sub>CE</sub> = -10V, I <sub>C</sub> = -1.0mA, f = 1.0kHz
Voltage Feedback Ratio	h <sub>re</sub>	0.1	8.0	x 10 <sup>-4</sup>	
Small Signal Current Gain	h <sub>fe</sub>	60	500	—	
Output Admittance	h <sub>oe</sub>	1.0	100	μS	
Current Gain-Bandwidth Product	f <sub>T</sub>	200	—	MHz	V <sub>CE</sub> = -10V, I <sub>C</sub> = -20mA, f = 100MHz
<b>SWITCHING CHARACTERISTICS</b>					
Delay Time	t <sub>d</sub>	—	15	ns	V <sub>CC</sub> = -30V, I <sub>C</sub> = -150mA, V <sub>BE(off)</sub> = -2.0V, I <sub>B1</sub> = -15mA
Rise Time	t <sub>r</sub>	—	20	ns	
Storage Time	t <sub>s</sub>	—	225	ns	V <sub>CC</sub> = -30V, I <sub>C</sub> = -150mA, I <sub>B1</sub> = I <sub>B2</sub> = -15mA
Fall Time	t <sub>f</sub>	—	30	ns	

Note: 6. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

**Typical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

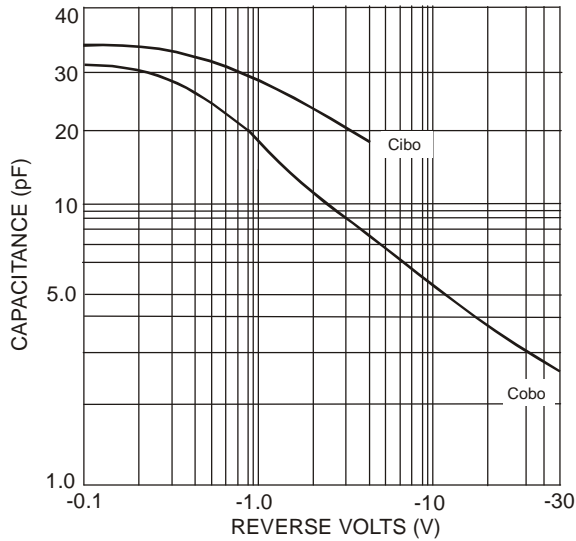


Fig. 2 Capacitances (Typical)

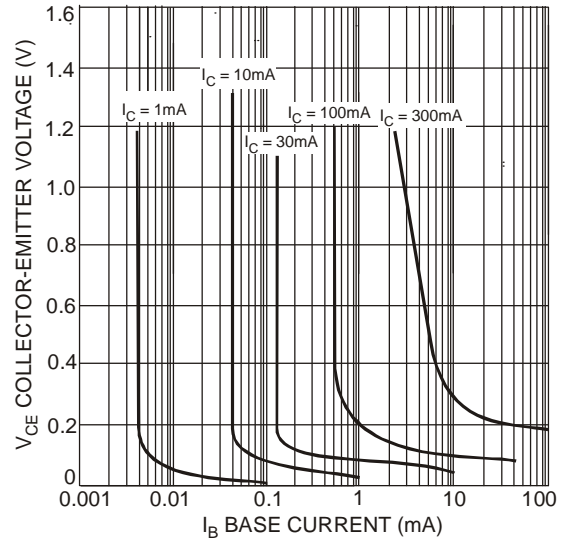


Fig. 3 Typical Collector Saturation Region

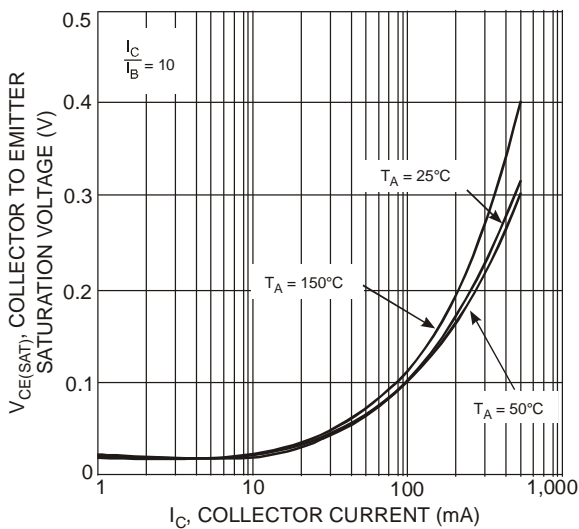


Fig. 4 Collector Emitter Saturation Voltage vs. Collector Current

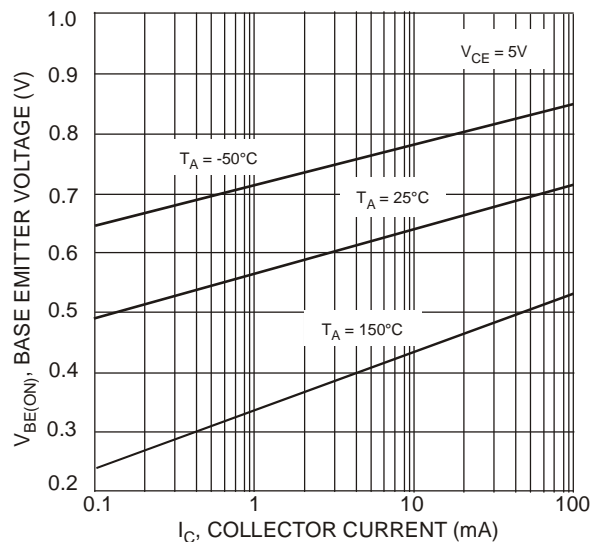


Fig. 5 Base-Emitter Voltage vs. Collector Current

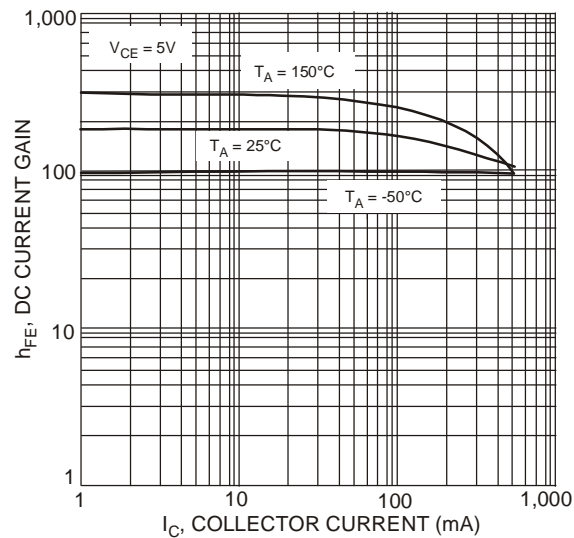


Fig. 6 DC Current Gain vs. Collector Current

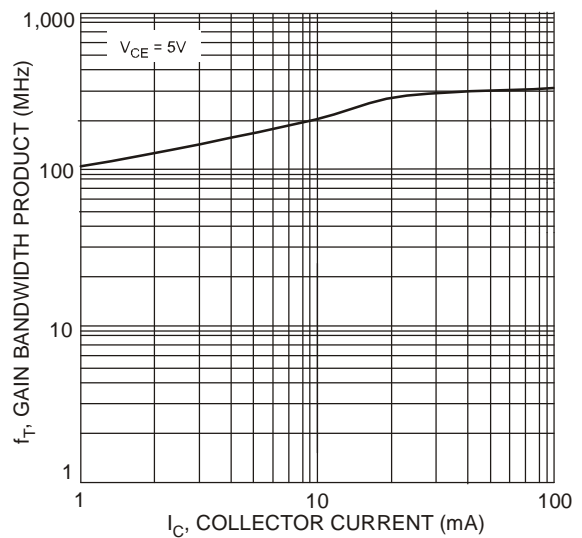
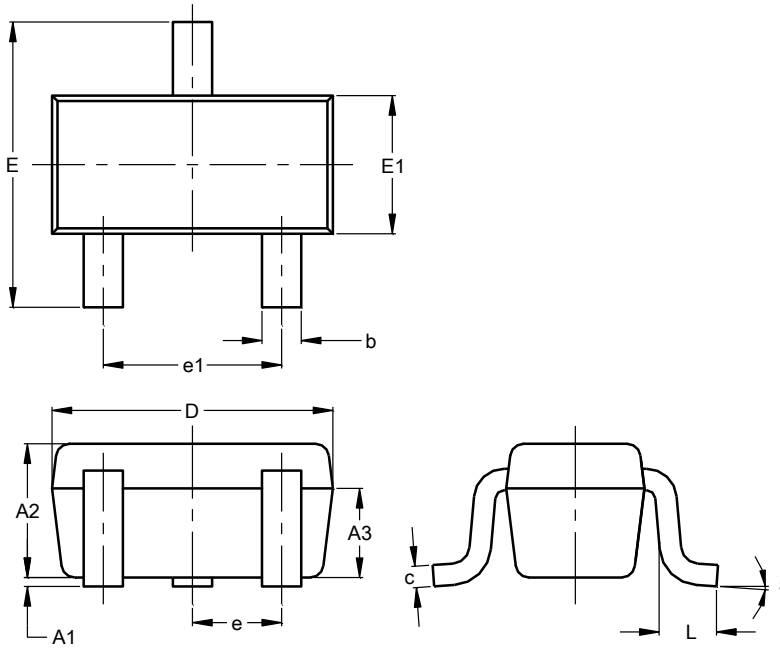


Fig. 7 Gain Bandwidth Product vs. Collector Current

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

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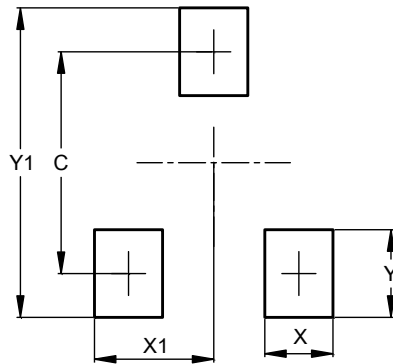


SOT523			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.60	0.80	0.75
A3	0.45	0.65	0.50
b	0.15	0.30	0.22
c	0.10	0.20	0.12
D	1.50	1.70	1.60
E	1.45	1.75	1.60
E1	0.75	0.85	0.80
e	0.50 BSC		
e1	0.90	1.10	1.00
L	0.20	0.40	0.33
a	0°	--	8°
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT523**



Dimensions	Value
C	1.29
X	0.40
X1	0.70
Y	0.51
Y1	1.80

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